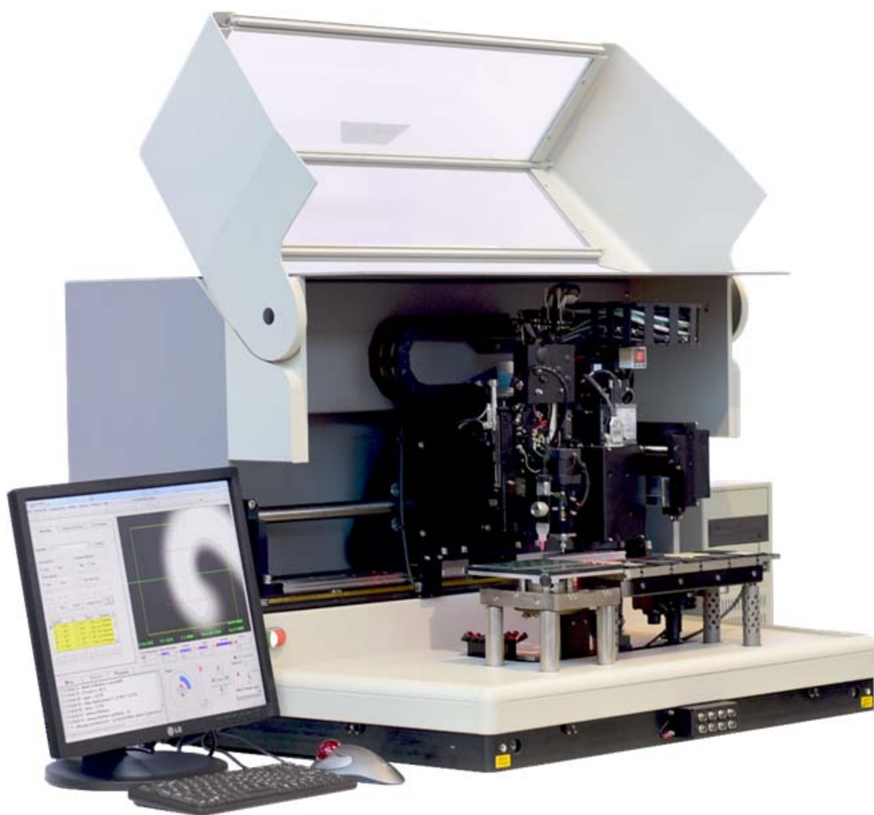
MicroAssembly Technologies, Ltd.

Model 6200
Semi-Automatic High Accuracy Die Attach System



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Performs **MCM, Flip Chip, Eutectic, Silver Glass, Ag Sintering etc** die attach applications.

Small footprint, **Table-Top** configuration. **Versatile** and **user friendly** machine using the same advanced software of Model 6400 running under Windows® on a PC platform.

Semi-automatic and Fully automatic process allowing highest flexibility and easy operation.

Very High Accuracy closed loop servo systems control the main motion axes. High resolution **Digital Vision** and **Image Processing** system.

Time-Pressure or **Volumetric Dispenser** for applying complex shapes of adhesive.

Double Dispenser for two different adhesives.

Stamping (Pin Transfer) 75 µm adhesive dots.

Die Presentation:
- Up to 9 Waffle/Gel packs 2“
- Up to 4 Tape & Reel feeders
- Up to one 8” Wafer with Manual Indexing
- Combinations of the above

Unique one-pass, wet **Die Stacking** capability with **BLT control** of the dice.

Capability to handle **MEMS** devices.

Experience with very large **Imaging Devices**.

Flip Chip process including chip flipping, bump fluxing and final alignment over a high resolution Up Looking Camera.

Eutectic MCM processes based on heated substrates with gas cover and heated pickup tools with provision of forming gas.

Ultrasonic bond head available for Gold to Gold Interconnection.

Specification Highlights	
Work Area	Up to 6” x 6”.
Die size range	0.006” to over 2”
Die Material	GaAs, Si, Glass, etc.
Substrates	Lead Frames, Ceramic, Silicon Wafers, PCB’s, Metal, TO cans, etc.
Pickup/Bond Force	40 to 9,000 grams.
Placement Accuracy	3 µm @ 3 sigma - application dependent.
Throughput	Up to 700 CPH – application dependent.
Size	0.97 x 0.85 x 0.65 m
Weight	About 200 kg

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